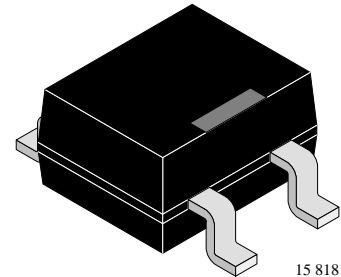




0.8A Surface Mount Bridge Rectifier

Features

- Rating to 1000V PRV
- Surge overload rating to 30A peak
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- Lead solderable per MIL–STD–202 method 208
- Lead: Snpb plated copper
- Plastic material – UL Recognition flammability classification 94V–0



Absolute Maximum Ratings

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Value	Unit
Repetitive peak reverse voltage =Working peak reverse voltage =DC Blocking voltage		HD01	V_{RRM} $=V_{RWM}$ $=V_R$	100	V
		HD02		200	V
		HD04		400	V
		HD06		600	V
		HD08		800	V
		HD10		1000	V
Peak forward surge current	$T_J=25^\circ\text{C}$, (JEDEC Method)		I_{FSM}	30	A
Average forward current	$T_A=40^\circ\text{C}$, mounted on CERAMIC P.C. board		I_{FAV}	0.8	A
Junction and storage temperature range			$T_j=T_{stg}$	-55...+150	$^\circ\text{C}$

Electrical Characteristics

$T_j = 25^\circ\text{C}$

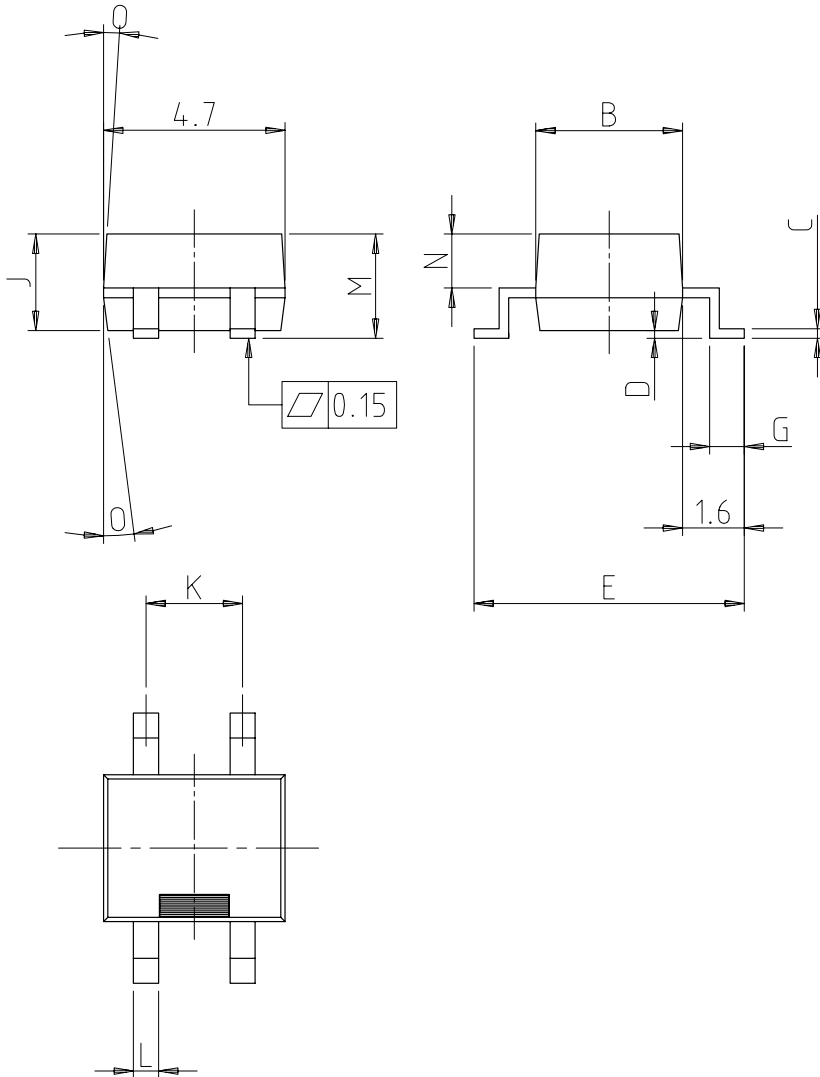
Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F=0.4\text{A}$		V_F			1	V
Reverse current	$T_J=125^\circ\text{C}$ $V_R=V_{RRM}$		I_R			5	μA
			I_R			500	μA
Diode capacitance	$V_R=4\text{V}$, $f=1\text{MHz}$		C_D		10		pF
Thermal resistance junction to ambient	mounted on CERAMIC P.C. board		R_{thJA}		75		K/W

HD01–HD10

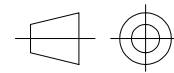
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Dimensions in mm



HD01 - HD10		
Dim	Min	Max
A	1.30	1.70
B	3.60	4.00
C	0.15	0.35
D	0.0	0.20
E	-	7.00
G	0.70	1.10
H	4.50	4.90
J	2.30	2.70
K	2.30	2.70
L	0.50	0.80
M	-	3.0
N	1.20	1.60
O	5°	
All Dimensions in mm		



technical drawings
according to DIN
specifications

15832

Case: molded plastic
Mounting position: any
Polarity: symbols molded on body
Approx. weight: 0.0044 ounces, 0.125 grams



Ozone Depleting Substances Policy Statement

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay-Telefunken products for any unintended or unauthorized application, the buyer shall indemnify Vishay-Telefunken against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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